## **IN THE SPECIFICATION:**

Please amend the specification as follows (reference is made to the lines as numbered).

Please amend Page 3, the second paragraph beginning on line 15 to read as follows:

The method in accordance with the invention for application of a layer of admixture (additive) in the web former unit of a board machine, the method for manufacture of board, and the board are mainly characterized in what is stated in the patent claims.

Marked-up version of Page 3, the second paragraph beginning on line 15 of the specification as amended:

The method in accordance with the invention for application of a layer of admixture (additive) in the web former unit of a board machine, the method for manufacture of board, and the board are mainly characterized in what is stated in the patent claims.

for manufacture of board and in which the stock flow produced out of the same fresh stock is

divided into two component flows. To the face that will be placed against the face of the layer to

Fig. 1 illustrates a preferred embodiment of the invention, which is in particular suitable

be combined, the necessary admixtures (additives) are added in order to increase the fines content in the layer and to promote the bond strength between the faces to an optimal extent at an optimal point. The component flows are passed into a multi-layer headbox and from it into a gap former. In this way, good properties of formation and strength and good internal bond strength are obtained for the board. Thus, out of the same fresh stock 11, two component flows 12<sub>1</sub> and 12<sub>2</sub> are produced. To the component flow 12<sub>1</sub>, out of which the face will be formed that will be placed against the face of the layer to be combined, at the point 14<sub>1</sub> before the pump 22, at the point 14<sub>2</sub> after the pump 22, and/or at the point 14<sub>3</sub> after the machine screen 33, the admixtures (additives) are added in order to increase the fines content in the layer and the bond strength

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between the faces. After this the component flows 12<sub>1</sub> and 12<sub>2</sub> are passed into the multi-layer

headbox 44, which comprises, in the conventional way, inlet headers, a tube manifold connected

with each inlet header, an intermediate chamber connected with the tube manifold, a turbulence

separate the layers in said slice cone. From the headbox the web is transferred into the former, in

which 55<sub>1</sub> represents the first forming wire, 55<sub>2</sub> the second forming wire, 66<sub>1</sub> represents a former

generator and turbulence tubes, a slice cone after the turbulence generator, and vanes that

roll, and 66<sub>2</sub> the forming roll.

Marked-up version of Page 3, the fourth paragraph bridging to Page 4 of the specification as amended:

Fig. 1 illustrates a preferred embodiment of the invention, which is in particular suitable for manufacture of board and in which the stock flow produced out of the same fresh stock is divided into two component flows. To the face that will be placed against the face of the layer to be combined, the necessary admixtures (additives) are added in order to increase the fines content in the layer and to promote the bond strength between the faces to an optimal extent at an optimal point. The component flows are passed into a multi-layer headbox and from it into a gap former. In this way, good properties of formation and strength and good internal bond strength are obtained for the board. Thus, out of the same fresh stock 11, two component flows 12, and 12, are produced. To the component flow 121, out of which the face will be formed that will be placed against the face of the layer to be combined, at the point 14, before the pump 22, at the point 142 after the pump 22, and/or at the point 143 after the machine screen 33, the admixtures (additives) are added in order to increase the fines content in the layer and the bond strength between the faces. After this the component flows 12<sub>1</sub> and 12<sub>2</sub> are passed into the multi-layer headbox 44, which comprises, in the conventional way, inlet headers, a tube manifold connected with each inlet header, an intermediate chamber connected with the tube manifold, a turbulence generator and turbulence tubes, a slice cone after the turbulence generator, and vanes that separate the layers in said slice cone. From the headbox the web is transferred into the former, in which 55<sub>1</sub> represents the first forming wire, 55<sub>2</sub> the second forming wire, 66<sub>1</sub> represents a former roll, and 66<sub>2</sub> the forming roll.

## Please amend Page 5, the first full paragraph beginning on line 6 to read as follows:

Fig. 4 shows a second preferred combination in accordance with the invention, in which the layers 13<sub>1</sub> and 13<sub>2</sub> that contain an admixture (additive) and that are to be combined are introduced in to two separate multi-layer headboxes, herein twin-layer headboxes 44<sub>3</sub>, 44<sub>4</sub>, and the webs that contain admixtures (additives) are passed into gap formers and then combined with each other. When two layers that contain admixtures (additives) are combined, a stronger bonding layer is obtained, which is necessary in applications that require higher strength. As shown in Fig. 4, the formation of layer 13<sub>2</sub> is conducted in an upper wire unit defined by wire 55<sub>3</sub>, wire 55<sub>4</sub> and twin-layer headbox 44<sub>4</sub>.



Marked-up version of Page 5, the first full paragraph beginning on line 6 of the specification as amended:

Fig. 4 shows a second preferred combination in accordance with the invention, in which the layers 13<sub>1</sub> and 13<sub>2</sub> that contain an admixture (additive) and that are to be combined are introduced in to two separate multi-layer headboxes, herein twin-layer headboxes 44<sub>3</sub>, 44<sub>4</sub>, and the webs that contain admixtures (additives) are passed into gap formers and then combined with each other. When two layers that contain admixtures (additives) are combined, a stronger bonding layer is obtained, which is necessary in applications that require higher strength. As shown in Fig. 4, the formation of layer 13<sub>2</sub> is conducted in an upper wire unit defined by wire 55<sub>3</sub>, wire 55<sub>4</sub> and twin-layer headbox 44<sub>4</sub>.